

Title (en)

MINIATURE RF AND MICROWAVE COMPONENTS AND METHODS FOR FABRICATING SUCH COMPONENTS

Title (de)

MINIATURISIERTE RF- UND MIKROWELLENBAUELEMENTE UND ZUGEHÖRIGES HERSTELLUNGSVERFAHREN

Title (fr)

COMPOSANTS RF ET ELECTROMAGNETIQUES MINIATURES ET PROCEDES DE FABRICATION DESDITS COMPOSANTS

Publication

**EP 1520321 A1 20050406 (EN)**

Application

**EP 03742306 A 20030627**

Priority

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- US 39253102 P 20020627
- US 41537402 P 20021001
- US 30952102 A 20021203
- US 46450403 P 20030421
- US 43451903 A 20030507
- US 43449703 A 20030507
- US 43410303 A 20030507
- US 43429503 A 20030507
- US 47655403 P 20030606

Abstract (en)

[origin: WO2004004061A1] RF and microwave radiation directing or controlling components are provided that may be monolithic, that may be formed from a plurality of electrodeposition operations and/or from a plurality of deposited layers of material, that may include switches, inductors, antennae, transmission lines, filters, hybrid couplers, antenna arrays and/or other active or passive components. Components may include non-radiation-entry and non-radiation-exit channels that are useful in separating sacrificial materials from structural materials. Preferred formation processes use electrochemical fabrication techniques (e.g. including selective depositions, bulk depositions, etching operations and planarization operations) and post-deposition processes (e.g. selective etching operations and/or back filling operations).

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IPC 8 full level

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